



LOW VCE(SAT) NPN SURFACE-MOUNT TRANSISTOR

Features

- Epitaxial Planar Die Construction
- Low Collector-Emitter Saturation Voltage
- Ideal for Low Power Amplification and Switching
- Complementary PNP Type Available (2DB1694)
- Ultra-Small Surface-Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

Mechanical Data

- Package: SOT323
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram
- Weight: 0.006 grams (Approximate)



Ordering Information (Note 4)

Part Number	Package	Packing		
Part Number	Package	Qty.	Carrier	
2DD2656-7	SOT323	3000	Tape & Reel	

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

RN1	ΥM

RN1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: L = 2024) M = Month (ex: 9 = September)

Device Schematic

Date Code Key

Year	2008	-	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	V	-	L	М	Ν	Р	R	S	Т	U	V	W
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	30	V
Collector-Emitter Voltage	VCEO	30	V
Emitter-Base Voltage	VEBO	6	V
Collector Current - Continuous	lc	1	А
Peak Pulse Collector Current	Ісм	2	A

Thermal Characteristics

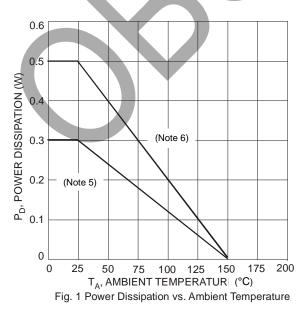
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) @ $T_A = +25^{\circ}C$	PD	300	mW
Thermal Resistance, Junction to Ambient (Note 5) @ T _A = +25°C	R _{0JA}	417	°C/W
Power Dissipation (Note 6) @ $T_A = +25^{\circ}C$	PD	500	mW
Thermal Resistance, Junction to Ambient (Note 6) @ T _A = +25°C	Reja	250	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	٥°

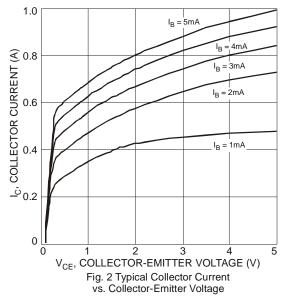
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

			_			
Characteristic	Symbol	Min	Тур	Max	Unit	Conditions
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	30	—	—	V	$I_{C} = 10 \mu A, I_{E} = 0$
Collector-Emitter Breakdown Voltage (Note 7)	V(BR)CEO	30	-		V	$I_{C} = 1 m A$, $I_{B} = 0$
Emitter-Base Breakdown Voltage	V(BR)EBO	6	_		V	$I_E = 10 \mu A$, $I_C = 0$
Collector Cutoff Current	Ісво		-	0.1	μA	Vcb = 15V, IE = 0
Emitter Cutoff Current	IEBO	-	-	0.1	μA	$V_{EB} = 6V, I_{C} = 0$
ON CHARACTERISTICS (Note 7)						
Collector-Emitter Saturation Voltage	V _{CE(sat)}	-	100	350	mV	$I_{C} = 500 \text{mA}, I_{B} = 25 \text{mA}$
DC Current Gain	hfe	270	_	680	_	$V_{CE} = 2V, I_{C} = 100 \text{mA}$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	Cobo	_	5	_	pF	$V_{CB} = 10V, I_E = 0$ f = 1MHz
Current Gain-Bandwidth Product	fτ	_	270	_	MHz	$V_{CE} = 2V$, $I_C = 100$ mA f = 100MHz

Notes:

5. Device mounted on FR-4 PCB with minimum recommended pad layout. 6. Device mounted on FR-4 PCB with 1 inch² copper pad layout. 7. Measured under pulsed conditions. Pulse width = 300µs. Duty cycle \leq 2%.







2DD2656

 $T_A = 150^{\circ}C$

100

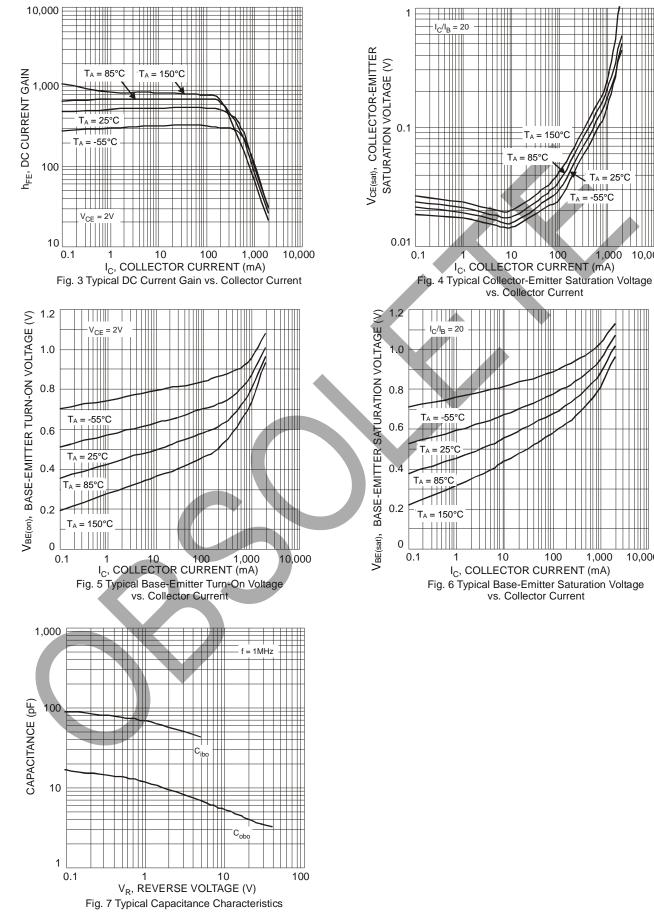
1,000

10,000

 $T_A = 25^{\circ}C$ $T_A = -55^{\circ}C$

1,000

10,000

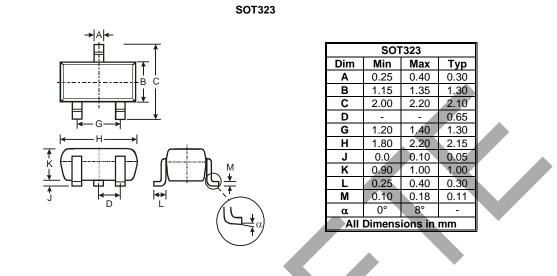




2DD2656

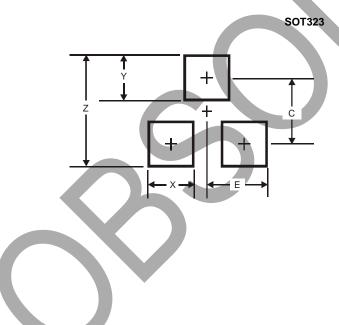
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
Z	2.8
Х	0.7
Y	0.9
С	1.9
E	1.0



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